

N-Ch 20V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

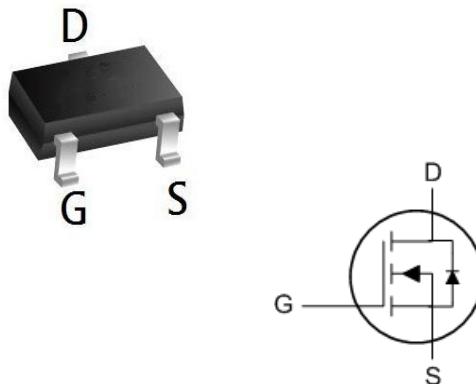


BVDSS	RDS(on)	ID
20V	35mΩ	3.6A

Description

The XR2302B is the high cell density trenched N-ch MOSFETs, which provides excellent RDS(on) and efficiency for most of the small power switching and load switch applications. The XR2302B meet the RoHS and Green Product requirement with full function reliability approved.

SOT23 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	3.6	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	1.5	A
I _{DM}	Pulsed Drain Current ²	12	A
P _D @T _A =25°C	Total Power Dissipation ³	1.05	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	112	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	---	°C/W

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Electrical Characteristics

 $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	--	--	1	μA
		$V_{DS} = 16 \text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -10 \text{ V}, V_{DS} = 0 \text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.45	-	1.1	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 3.5 \text{ A}$	--	35	45	$\text{m}\Omega$
		$V_{GS} = 2.5 \text{ V}, I_D = 2.0 \text{ A}$	-	46	57	

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	--	180	-	pF
C_{oss}	Output Capacitance		--	37	-	pF
C_{rss}	Reverse Transfer Capacitance		--	34	-	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 5 \text{ V}, V_{DS} = 10 \text{ V}, I_D = 3 \text{ A}, R_G = 6 \Omega, R_L = 2.7 \Omega$	--	4.5	--	ns
t_r	Turn-On Rise Time		--	31	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	12	--	ns
t_f	Turn-Off Fall Time		--	4.0	--	ns
Q_g	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_D = 3 \text{ A}, V_{GS} = 5 \text{ V}$	--	6.23	--	nC
Q_{gs}	Gate-Source Charge		--	6	--	nC
Q_{gd}	Gate-Drain Charge		--	0.5	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_s	Maximum Continuous Drain-Source Diode Forward Current	--	--	3.5	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	10.5	A
V_{SD}	Drain to Source Diode Forward Voltage, $V_{GS} = 0 \text{ V}, I_{SD} = 3.5 \text{ A}, T_J = 25^\circ\text{C}$	--	--	1.2	V

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062 inch
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

N- Channel Typical Characteristics

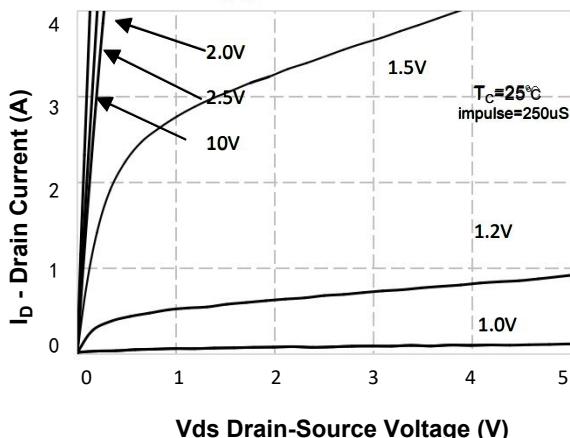


Figure 1. On-Region Characteristics

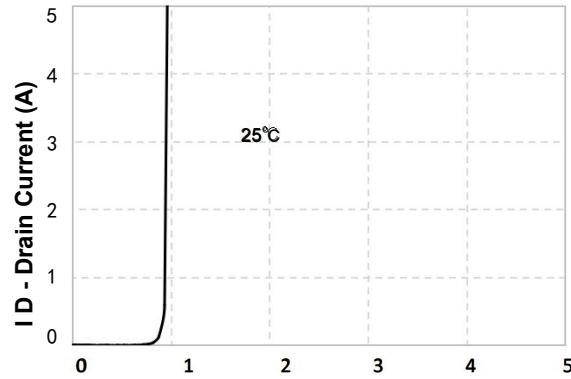


Figure 2. Transfer Characteristics

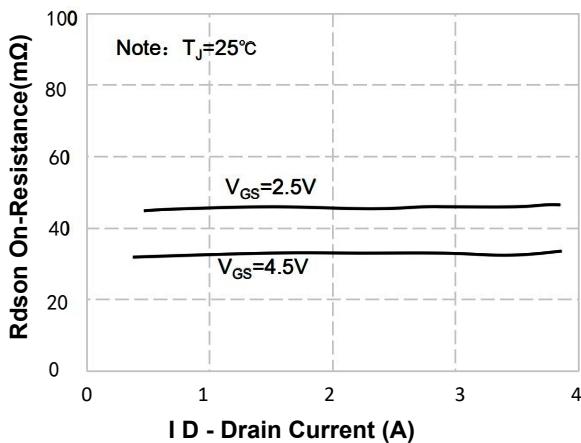


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

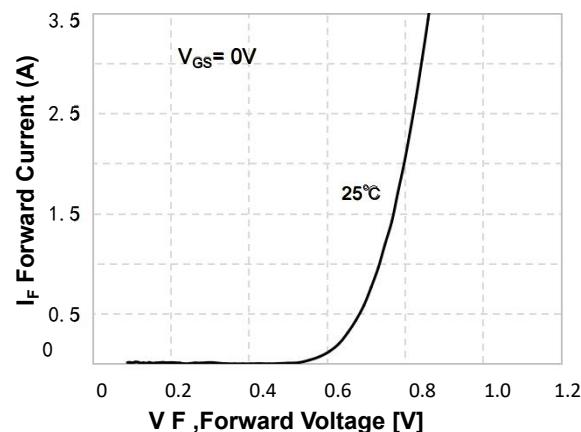


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

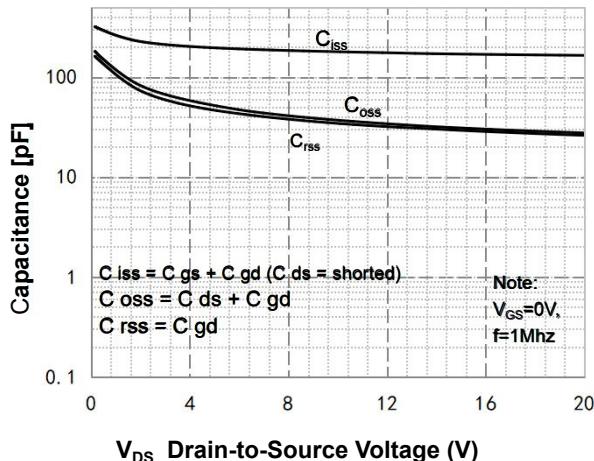


Figure 5. Capacitance Characteristics

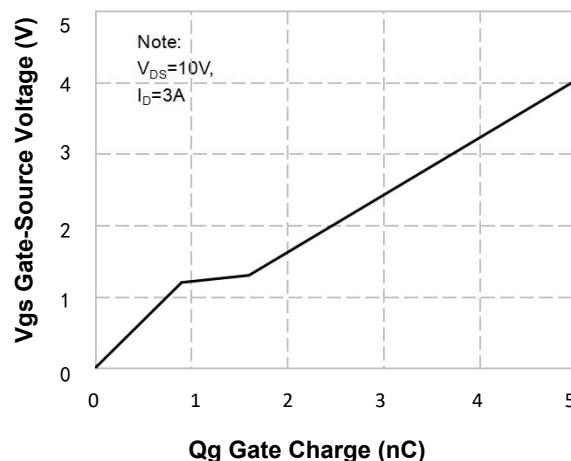


Figure 6. Gate Charge Characteristics

N- Channel Typical Characteristics (Continued)

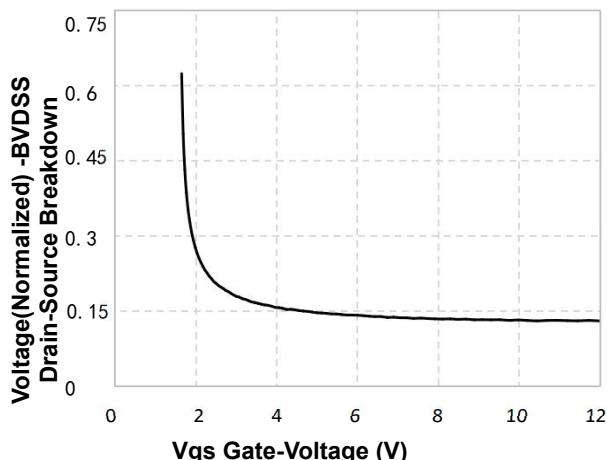


Figure 7. Breakdown Voltage Variation
vs Gate-Voltage

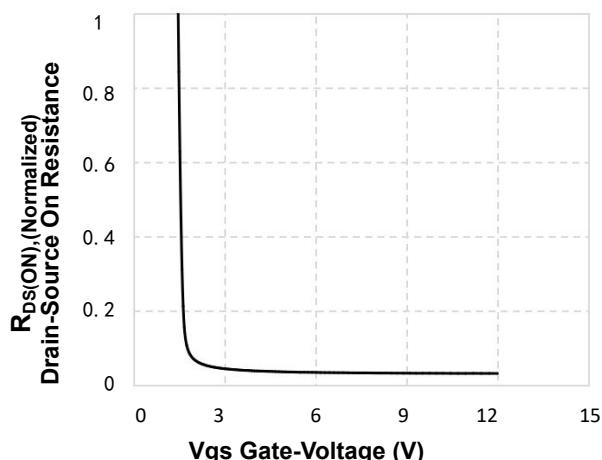


Figure 8. On-Resistance Variation
vs Gate Voltage

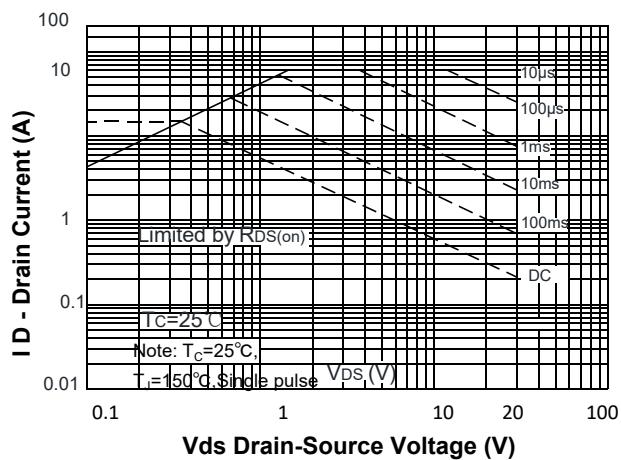


Figure 9. Maximum Safe Operating Area

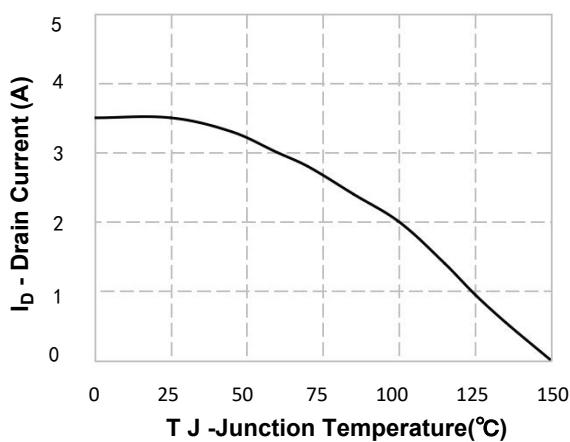


Figure 10. Maximum Continuous Drain Current vs Case Temperature

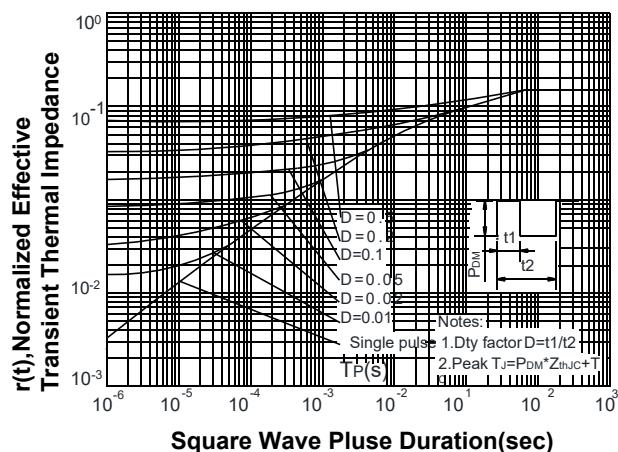
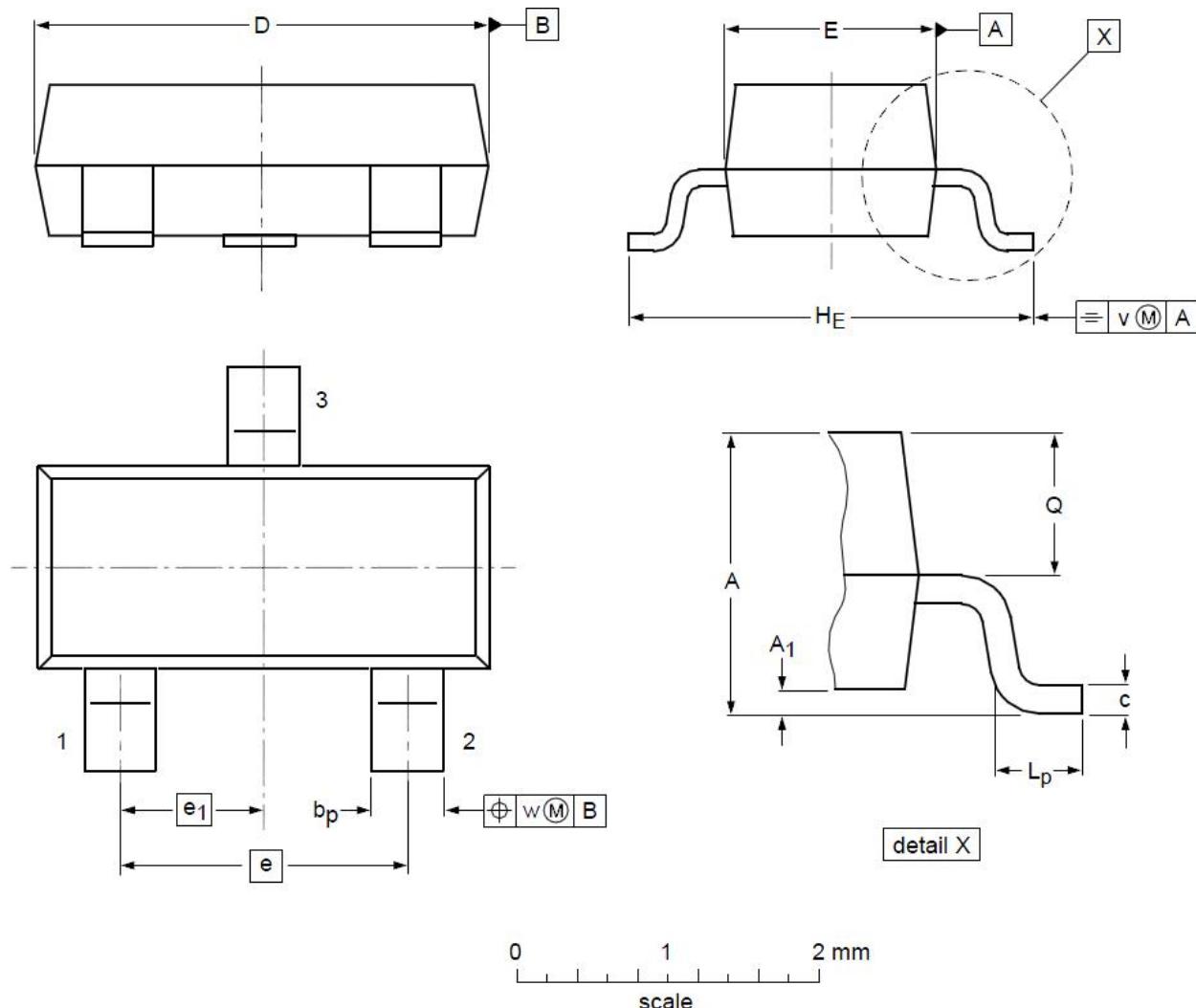


Figure 11. Transient Thermal Response Curve

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SOT23 Mechanical Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A₁	0.01	0.05	0.10
b_p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e₁	--	0.95	--
H_E	2.25	2.40	2.55	L_p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				